# onsemi

# **MOSFET** – N-Channel, POWERTRENCH<sup>®</sup>

V <sub>DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> MAX	
100 V	9.7 mΩ @ 10 V	74 A	

100 V, 74 A, 12 m $\Omega$ 

# **FDP120N10**

#### Description

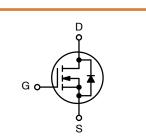
This N-Channel MOSFET is produced using **onsemi**'s advanced POWERTRENCH process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

#### Features

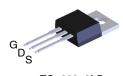
- $R_{DS(on)} = 9.7 \text{ m}\Omega \text{ (Typ.)} @ V_{GS} = 10 \text{ V}, I_D = 74 \text{ A}$
- Fast Switching Speed
- Low Gate Charge
- High Performance Trench Technology for Extremely Low RDS(on)
- High Power and Current Handling Capability RoHS Compliant
- This Device is Pb-Free, Halide Free and RoHS Compliant

#### Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- Battery Protection Circuit
- Motor Drives and Uninterruptible Power Supplies
- Micor Solar Inverter

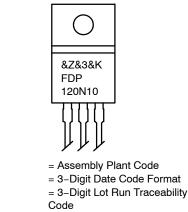


**N-Channel MOSFET** 



TO-220-3LD CASE 340AT

#### MARKING DIAGRAM



FDP120N10 = Specific Device Code

&Z

&З

&K

#### **ORDERING INFORMATION**

Device	Package	Shipping
FDP120N10	TO-220 (Pb-Free)	800 Units / Tube

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = $25^{\circ}$ C unless otherwise noted)

Symbol	Parameter		FDP120N10	Unit
V <sub>DSS</sub>	Drain to Source Voltage		100	V
V <sub>GSS</sub>	Gate to Source Voltage		±20	V
I <sub>D</sub>	Drain Current	– Continuous (T <sub>C</sub> = 25°C, Silicon Limited)	74	А
		– Continuous (T <sub>C</sub> = 100°C, Silicon Limited)	52	
I <sub>DM</sub>	Drain Current	– Pulsed (Note 1)	296	А
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		198	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		6.0	V/ns
PD	Power Dissipation	(T <sub>C</sub> = 25°C)	170	W
		– Derate Above 25°C	1.14	W/°C
TJ, T <sub>STG</sub>	Operating and Storage Temperature Range		–55 to +175	°C
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. L = 0.11 mH,  $I_{AS} = 60 \text{ A}$ ,  $V_{DD} = 50 \text{ V}$ ,  $R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}\text{C}$ . 3.  $I_{SD} \le 74 \text{ A}$ ,  $di/dt \le 200 \text{ A}/\mu\text{s}$ ,  $V_{DD} \le \text{BV}_{DSS}$ , starting  $T_J = 25^{\circ}\text{C}$ .

#### THERMAL CHARACTERISTICS

Symbol	Parameter	FDP120N10	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.88	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

#### ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARA	ACTERISTICS					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D$ = 250 $\mu A,V_{GS}$ = 0 V, $T_C$ = 25°C	100	-	-	V
$\frac{\Delta \text{BV}_{\text{DSS}}}{\Delta \text{T}_{\text{J}}}/$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \ \mu\text{A}$ , Referenced to $25^{\circ}\text{C}$	-	0.1	_	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 100 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1	μΑ
		$V_{DS}$ = 100 V, $V_{GS}$ = 0 V, $T_{C}$ = 150°C	-	-	500	
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS}=\pm 20 \text{ V},  \text{V}_{DS}=0 \text{ V}$	-	-	±100	nA
ON CHARA	CTERISTICS					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \ \mu A$	2.5	-	4.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 74 A	-	9.7	12	mΩ
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 74 A	-	105	-	S
YNAMIC C	HARACTERISTICS					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25 V, V_{GS} = 0 V,$	-	4215	5605	pF
C <sub>oss</sub>	Output Capacitance	f = 1 MHz	-	405	540	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	170	255	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	$V_{DS} = 80 \text{ V}, \text{ I}_{D} = 74 \text{ A},$	-	66	86	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V (Note 4)	-	26	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		-	20	-	nC
WITCHING	CHARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ = 50 V, I <sub>D</sub> = 74 A, $V_{GS}$ = 10 V, R <sub>G</sub> = 4.7 $\Omega$ (Note 4)	-	27	64	ns
t <sub>r</sub>	Turn–On Rise Time		-	105	220	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	39	88	ns
t <sub>f</sub>	Turn-Off Fall Time		-	15	40	ns
RAIN-SOU	IRCE DIODE CHARACTERISTICS					
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	74	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	296	Α
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 74 A	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 V, I_{SD} = 74 A,$ $dI_F/dt = 100 A/\mu s$	-	44	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		_	67	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. \*Package limitation current is 120 A. 4. Essentially independent of operating temperature typical characteristics.

#### **TYPICAL PERFORMANCE CHARACTERISTICS**

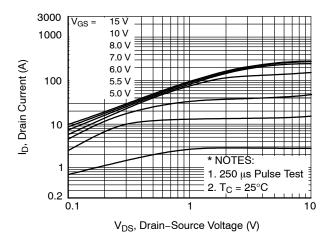


Figure 1. On–Region Characteristics

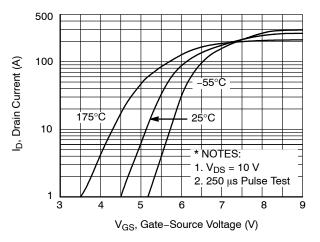


Figure 2. Transfer Characteristics

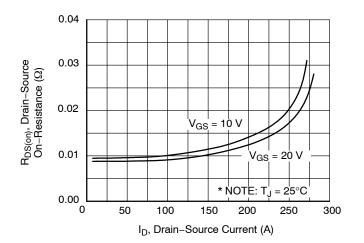


Figure 3. On–Resistance Variation vs. Drain Current and Gate Voltage

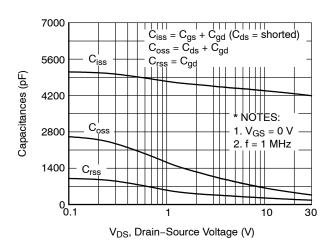


Figure 5. Capacitance Characteristics

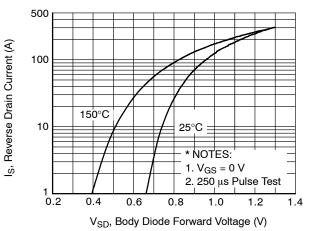


Figure 4. Body Diode Forward Voltage Variation vs. Source Current And Temperature

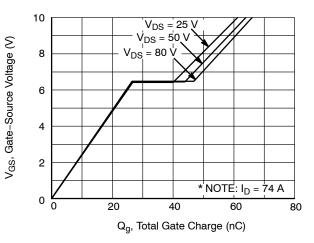
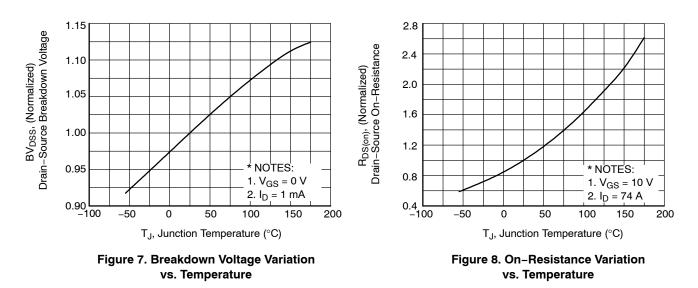


Figure 6. Gate Charge Characteristics

#### TYPICAL PERFORMANCE CHARACTERISTICS (continued)



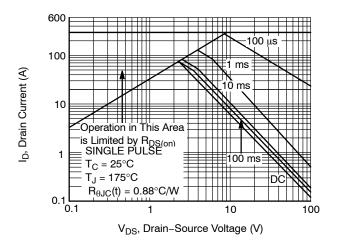


Figure 9. Maximum Safe Operating Area

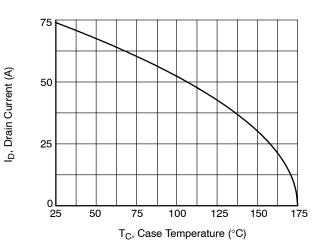


Figure 10. Maximum Drain Current vs. Case Temperature

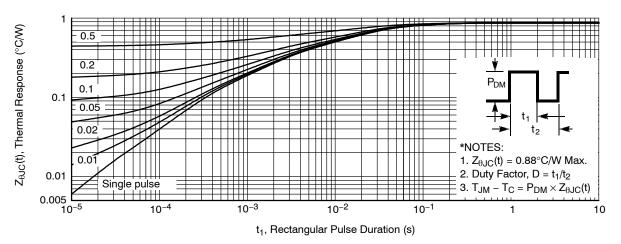


Figure 11. Transient Thermal Response Curve

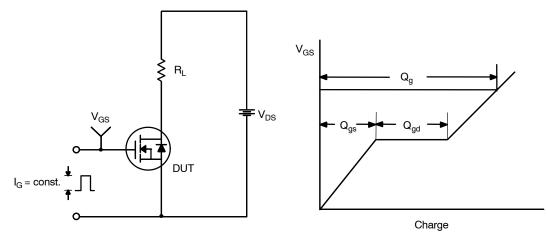


Figure 12. Gate Charge Test Circuit & Waveform

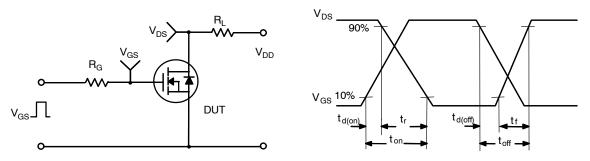


Figure 13. Resistive Switching Test Circuit & Waveforms

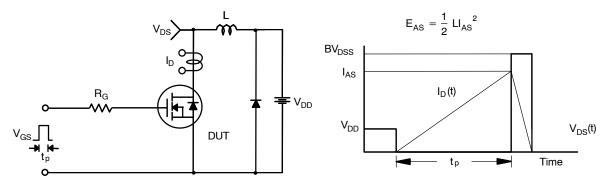


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

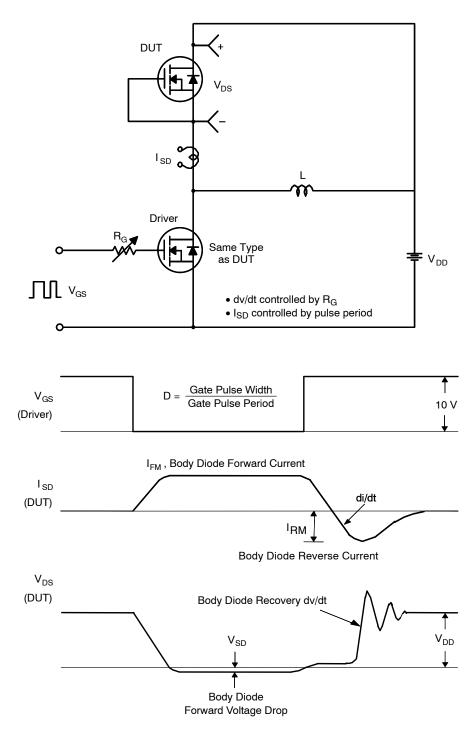
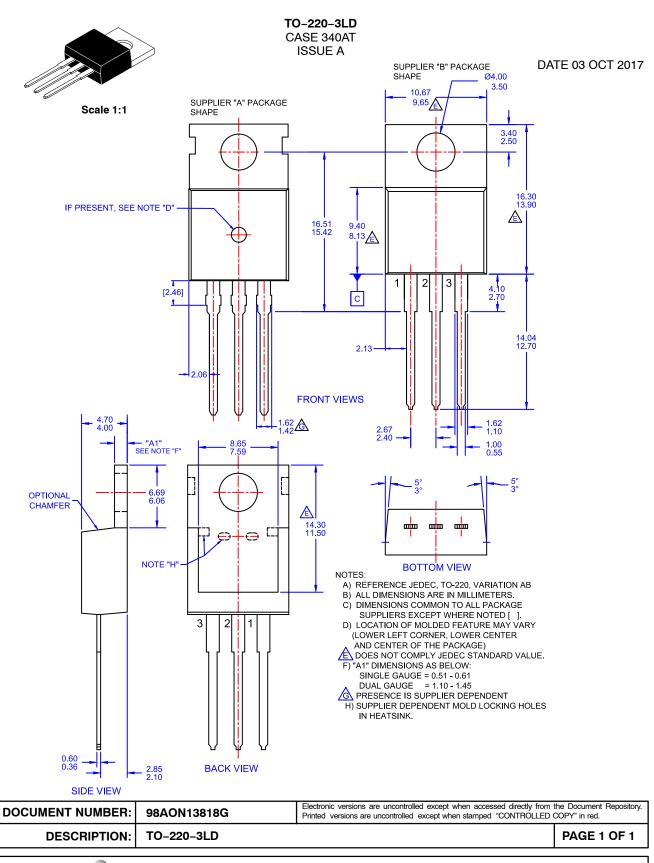


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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